

Qualification Results Summary
WIN 0.5µm pHEMT, MSL 3 Rating Change for LFCSP Package Devices

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	1496	Pass
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	897	Pass

* These samples were subjected to preconditioning (per j-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.

Qualification Results Summary
WIN 0.5µm pHEMT, MSL 3 Rating Change for MINI SO EP Package Devices

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	327	Pass
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	63	Pass

* These samples were subjected to preconditioning (per j-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.

Moisture Sensitivity Level Rating Change for GCS LFCSP

Qualification Results Summary

MSL-3 Rating Change for GCS LFCSP Device.

QUALIFICATION RESULTS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Solder Heat Resistance (SHR)*	JEDEC/ IPC J-STD-020	60	PASS
Temperature Cycling (TC)*	JEDEC JESD22-A104	175	PASS

*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.